

ABSTRACT

To provide an adhesive tape for semiconductor processing, which is capable of suppressing cracks of a chip even if used in DBG or LDBG. [Solution] An adhesive tape for semiconductor processing, which comprises a base material, a buffer layer that is provided on at least one surface side of the base material, and an adhesive layer that is provided on the other surface side of the base material. This adhesive tape is configured such that: the buffer layer has a Young's modulus of 10-400 MPa at 23°C and a rupture energy of 1-9 MJ/m³; and the Young's modulus of the base material at 23°C is higher than the above-mentioned Young's modulus of the buffer layer.

[Figure]